

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5252311

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RUINING FENG	11/14/2018
RECEIVING PARTY DATA	
Name:	ENPING YIFENG PLASTIC & MOULD CO., LTD.
Street Address:	1/F, NO. 3 DEPT., A9-1. AREA 3, ENPING INDUS. PARK
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State/Country:	CHINA
Postal Code:	529400
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29671350
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NAME OF SUBMITTER:	RICHARD M. MESCHER
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DATE SIGNED:	11/27/2018
Total Attachments: 1	
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PATENT ASSIGNMENT

Whereas, **Ruining Feng**, having a mailing address of A9-1 the 3rd Zone, Micang Industry Park, Enping, Jiangmen City, Guangdong Province 529400, China is the sole inventor of certain new and ornamental improvements in a "Toolbox", for which a United States design application is being contemporaneously filed;

And whereas, **Enping YiFeng Plastic & Mould Co., Ltd.**, a Chinese company having an address of 1/F, No. 3 Department, A9-1, Area 3, Enping Industrial Park, Jiangmen Industrial Transfer Park, Encheng Town, Enping, Jiangmen City, Guangdong Province 529400 China is desirous of acquiring the entire right, title and interest in, to and under the invention in the USA, the US design application, and any other US patent applications claiming priority therefrom;

Now, therefore, in accordance with my agreements with **Enping YiFeng Plastic & Mould Co., Ltd.**, and other good and valuable consideration, the receipt of which is hereby acknowledged, **I, Ruining Feng**, do hereby sell, assign and transfer to **Enping YiFeng Plastic & Mould Co., Ltd.** the entire right, title and interest in and to the invention of new and ornamental improvements in and to a "Toolbox" in the USA, the US design application, the invention therein described, and all rights appurtenant thereto and in all my US patent applications related thereto, including each of the following: the right to apply for any patent for the invention in the USA, any and all other applications for patent on the invention including all non-provisional, divisional, continuation, continuation-in-part, renewal, substitute and refiled or reissue applications based in whole or in part upon the invention or upon the patent applications or related thereto; any and all patents that may issue thereon in the USA, all to be held by **Enping YiFeng Plastic & Mould Co., Ltd.**, and its successors and assigns, all the same as I would have held had this Assignment not been made.

I hereby request and authorize the empowered officials of the USA to grant, issue and transfer any patent for the invention to **Enping YiFeng Plastic & Mould Co., Ltd.**, as assignee of the entire right, title and interest therein, in accordance with this instrument of assignment.

I hereby represent and warrant that there are no outstanding rights or interest inconsistent with the rights and interests granted herein; I bind myself and my heirs, executors, administrators and legal representatives to execute and deliver to **Enping YiFeng Plastic & Mould Co., Ltd.**, and its successors and assigns, any further documents or instruments and to perform any and all further acts that may be deemed necessary to enable it, and its successors and assigns, to file patent applications for said invention in the USA in which it may elect to file such applications, and to vest in **Enping YiFeng Plastic & Mould Co., Ltd.**, and its successors and assigns, the title herein conveyed, and to enable such title to be recorded in each application so that any patent issued thereon shall issue to **Enping YiFeng Plastic & Mould Co., Ltd.**, and its successors and assigns.

Inventor: **Ruining Feng**

Inventor's Signature: _____

Ruining Feng

Date Signed: _____

2018.11.14

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